

AP4435GYT-HF-VB Datasheet P-Channel 30 V (D-S) MOSFET

V_{DS}		-30	V
$R_{DS(on),typ}$	$V_{GS}=10V$	11	$m\Omega$
$R_{DS(on),typ}$	$V_{GS}=4.5V$	18	$m\Omega$
I_D		-45	A

FEATURES

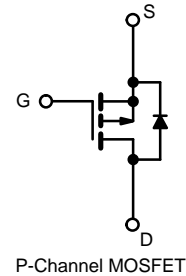
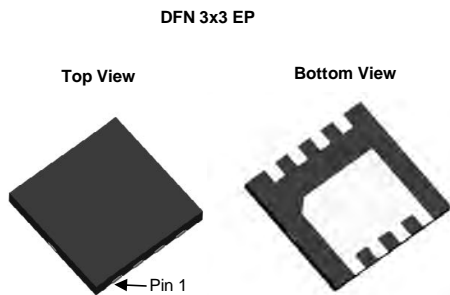
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- Low Thermal Resistance PowerPAK® Package with Small Size and Low 1.07 mm Profile
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Load Switch
- Adaptor Switch
- Notebook PC



ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)				
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	- 30	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current ($T_J = 150\text{ }^\circ\text{C}$)	$T_C = 25\text{ }^\circ\text{C}$	I_D	- 45	A
	$T_C = 70\text{ }^\circ\text{C}$		- 30	
	$T_A = 25\text{ }^\circ\text{C}$		- 14.4 ^{a, b}	
	$T_A = 70\text{ }^\circ\text{C}$		- 11.5 ^{a, b}	
Pulsed Drain Current		I_{DM}	- 60	
Continuous Source-Drain Diode Current	$T_C = 25\text{ }^\circ\text{C}$	I_S	- 35 ^e	
	$T_A = 25\text{ }^\circ\text{C}$		- 3.2 ^{a, b}	
Avalanche Current	L = 0.1 mH	I_{AS}	- 25	
Single-Pulse Avalanche Energy		E_{AS}	31.25	mJ
Maximum Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	P_D	52	W
	$T_C = 70\text{ }^\circ\text{C}$		43	
	$T_A = 25\text{ }^\circ\text{C}$		3.8 ^{a, b}	
	$T_A = 70\text{ }^\circ\text{C}$		2.4 ^{a, b}	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 50 to 150	$^\circ\text{C}$
Soldering Recommendations (Peak Temperature) ^{c, d}			260	

Notes:

- Surface mounted on 1" x 1" FR4 board.
- $t = 10\text{ s}$.
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- Package limited.
- Based on $T_C = 25\text{ }^\circ\text{C}$

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{a, b}	$t \leq 10$ s	R_{thJA}	26	33	°C/W
Maximum Junction-to-Case (Drain)	Steady State	R_{thJC}	1.9	2.4	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
 b. Maximum under Steady State conditions is 81 °C/W.

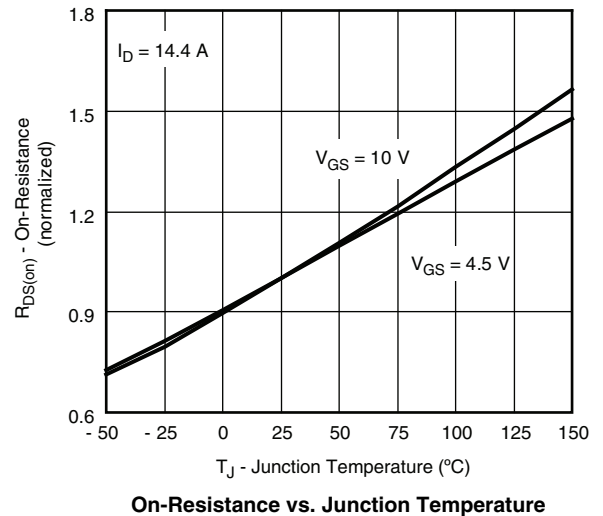
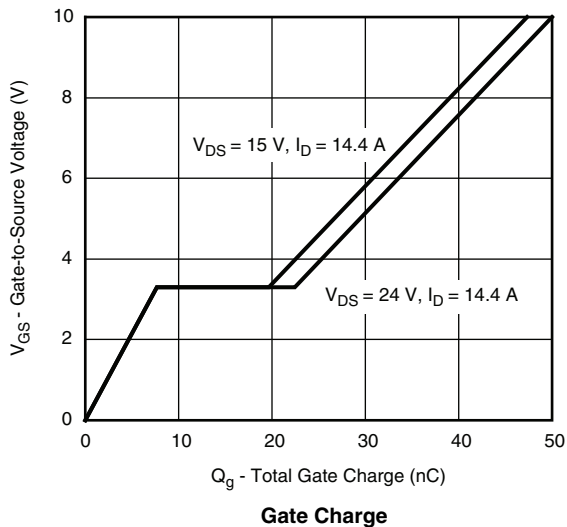
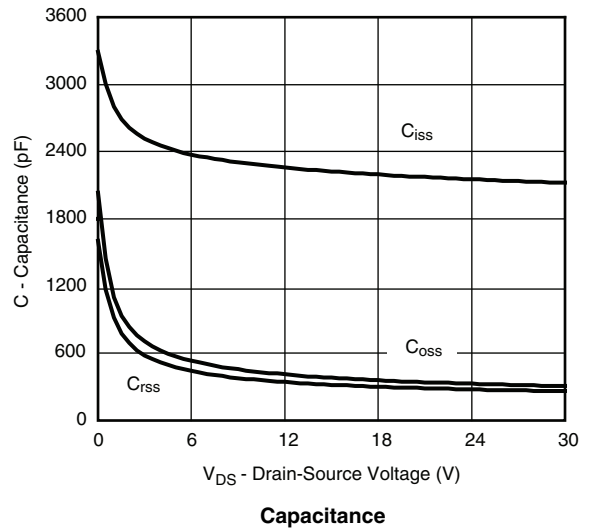
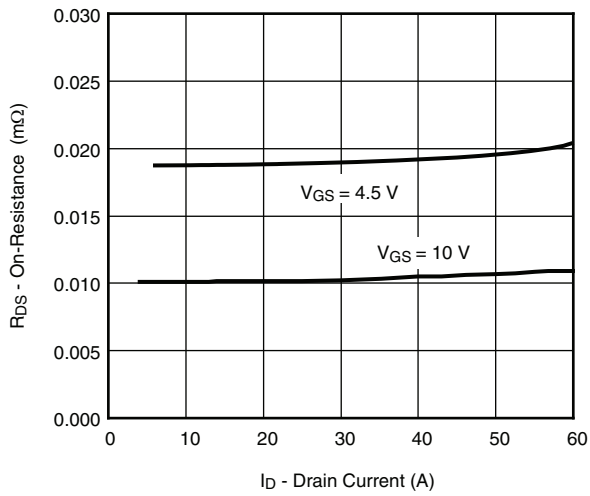
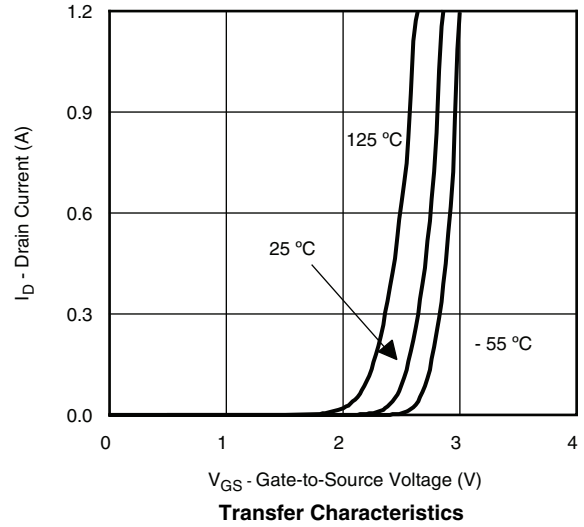
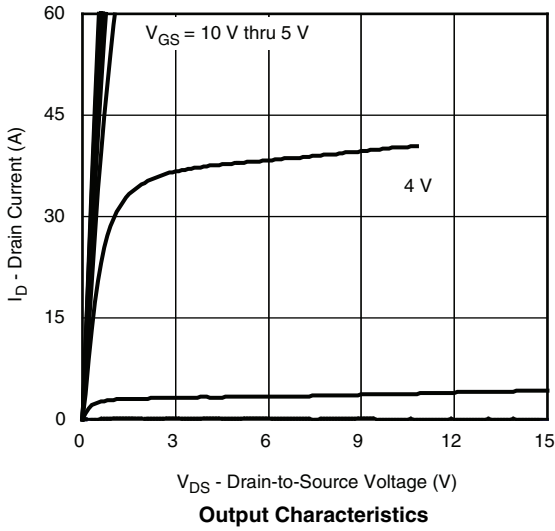
SPECIFICATIONS ($T_J = 25$ °C, unless otherwise noted)								
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit		
Static								
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0$ V, $I_D = -250$ μ A	- 30			V		
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = -250$ μ A		- 20		mV/°C		
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$		5					
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = -250$ μ A	- 1.5		- 2.8	V		
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0$ V, $V_{GS} = \pm 20$ V			± 100	nA		
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -30$ V, $V_{GS} = 0$ V			- 1	μ A		
		$V_{DS} = -30$ V, $V_{GS} = 0$ V, $T_J = 55$ °C			- 10			
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} \leq -5$ V, $V_{GS} = -10$ V	- 20			A		
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = -10$ V, $I_D = -14.4$ A		11		m Ω		
		$V_{GS} = -4.5$ V, $I_D = -11.5$ A		18				
Forward Transconductance ^a	g_{fs}	$V_{DS} = -15$ V, $I_D = -14.4$ A		37		S		
Dynamic^b								
Input Capacitance	C_{iss}	$V_{DS} = -15$ V, $V_{GS} = 0$ V, $f = 1$ MHz		2000		pF		
Output Capacitance	C_{oss}		385					
Reverse Transfer Capacitance	C_{rss}		322					
Total Gate Charge	Q_g	$V_{DS} = -15$ V, $V_{GS} = -10$ V, $I_D = -14.4$ A			15	nC		
Gate-Source Charge	Q_{gs}	$V_{DS} = -15$ V, $V_{GS} = -4.5$ V, $I_D = -14.4$ A			14			
Gate-Drain Charge	Q_{gd}		7					
Gate Resistance	R_g		9					
Turn-On Delay Time	$t_{d(on)}$	$f = 1$ MHz	0.4	1.8	3.6	Ω		
Rise Time	t_r		$V_{DD} = -15$ V, $R_L = 1.5$ Ω $I_D \cong -10$ A, $V_{GEN} = -4.5$ V, $R_g = 1$ Ω		50		75	ns
Turn-Off DelayTime	$t_{d(off)}$				43		65	
Fall Time	t_f				30		45	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -15$ V, $R_L = 1.5$ Ω $I_D \cong -10$ A, $V_{GEN} = -10$ V, $R_g = 1$ Ω			14	21		
Rise Time	t_r				14	21		
Turn-Off DelayTime	$t_{d(off)}$				9	18		
Fall Time	t_f				36	54		
Reverse Recovery Fall Time	t_a				10	20		
Reverse Recovery Rise Time	t_b							
Drain-Source Body Diode Characteristics								
Continuous Source-Drain Diode Current	I_S	$T_C = 25$ °C			- 35 ^e	A		
Pulse Diode Forward Current ^a	I_{SM}				- 60			
Body Diode Voltage	V_{SD}	$I_F = -10$ A		- 0.8	- 1.2	V		
Body Diode Reverse Recovery Time	t_{rr}	$I_F = -10$ A, $di/dt = 100$ A/ μ s, $T_J = 25$ °C		31	47	ns		
Body Diode Reverse Recovery Charge	Q_{rr}		30	45	nC			
Reverse Recovery Fall Time	t_a		15		ns			
Reverse Recovery Rise Time	t_b		16					

Notes:

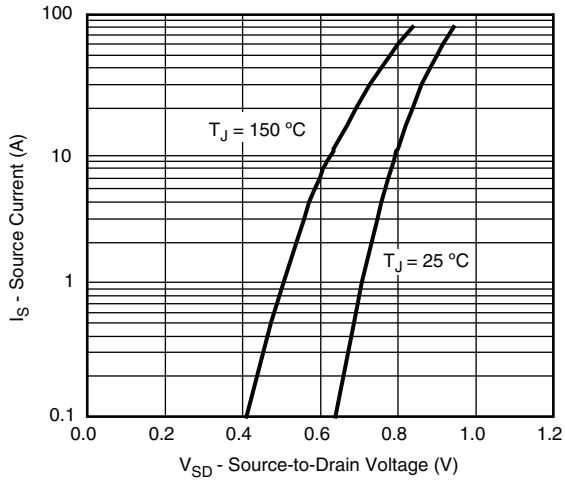
- a. Pulse test; pulse width ≤ 300 μ s, duty cycle ≤ 2 %.
 b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

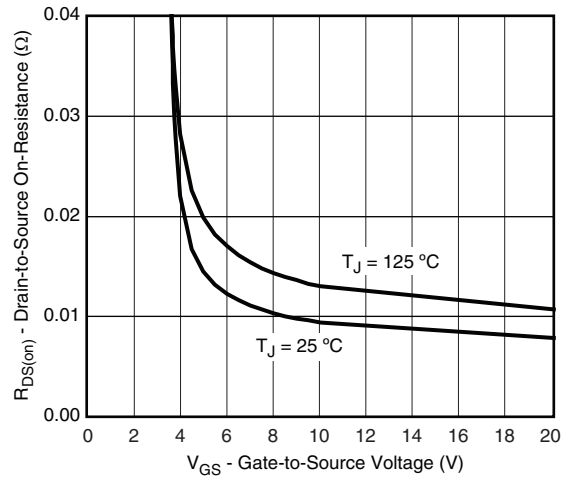
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



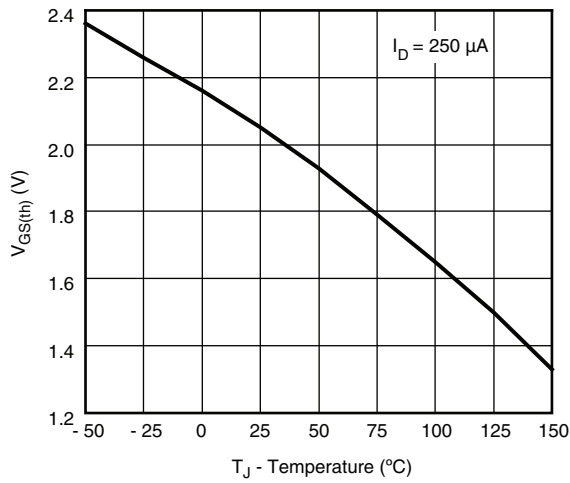
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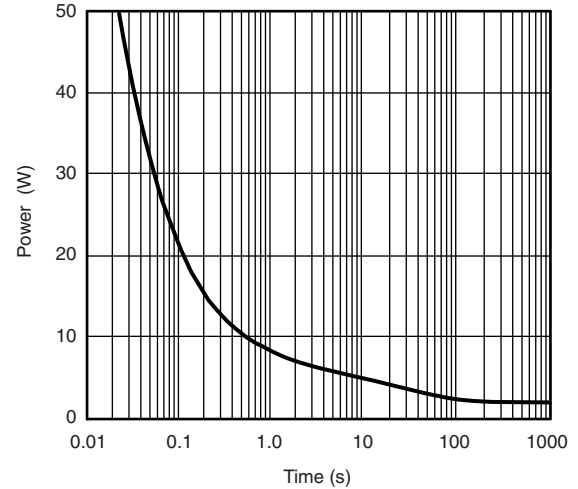
Source-Drain Diode Forward Voltage



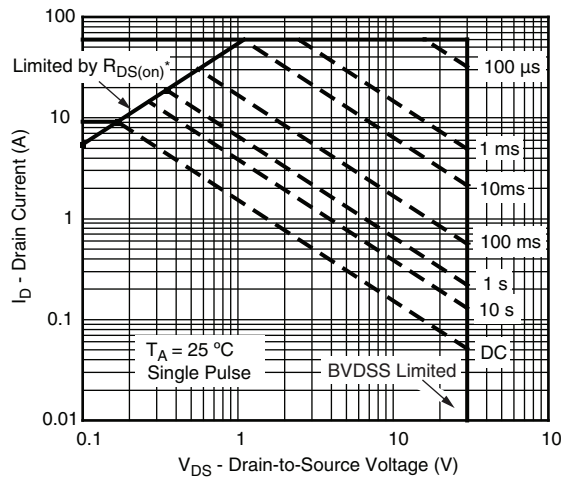
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

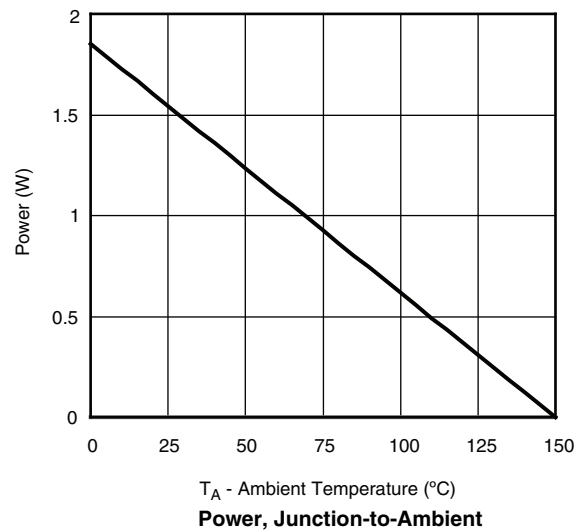
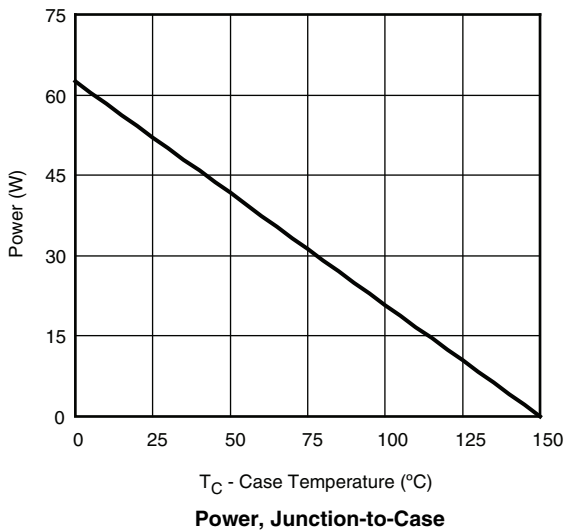
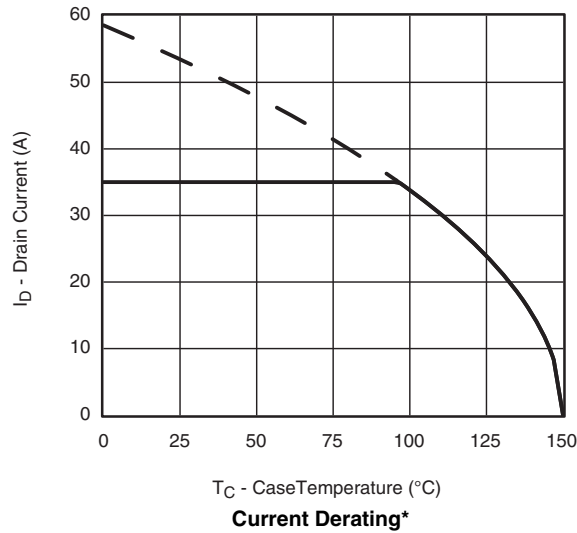


Single Pulse Power, Junction-to-Ambient



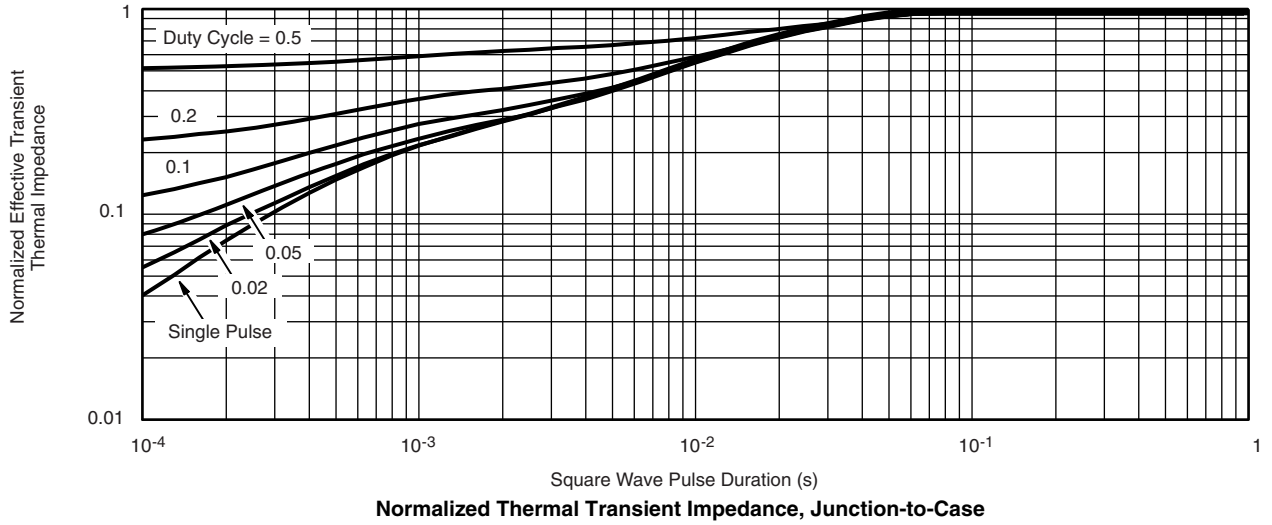
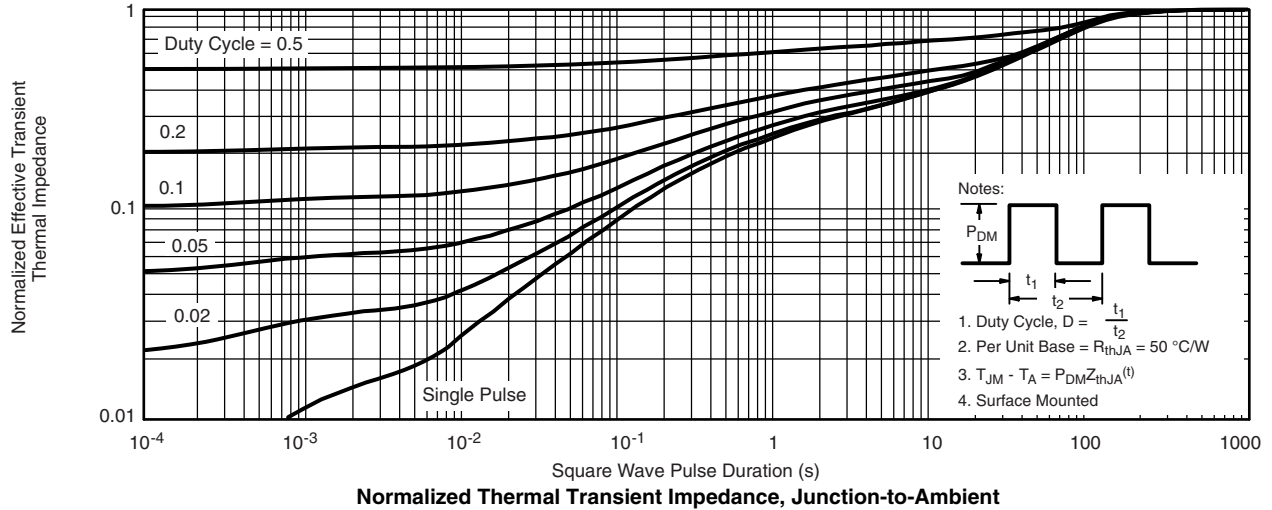
Safe Operating Area, Junction-to-Ambient

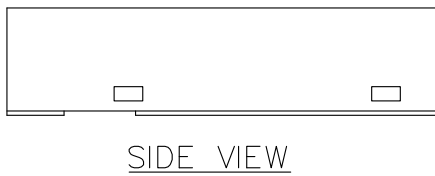
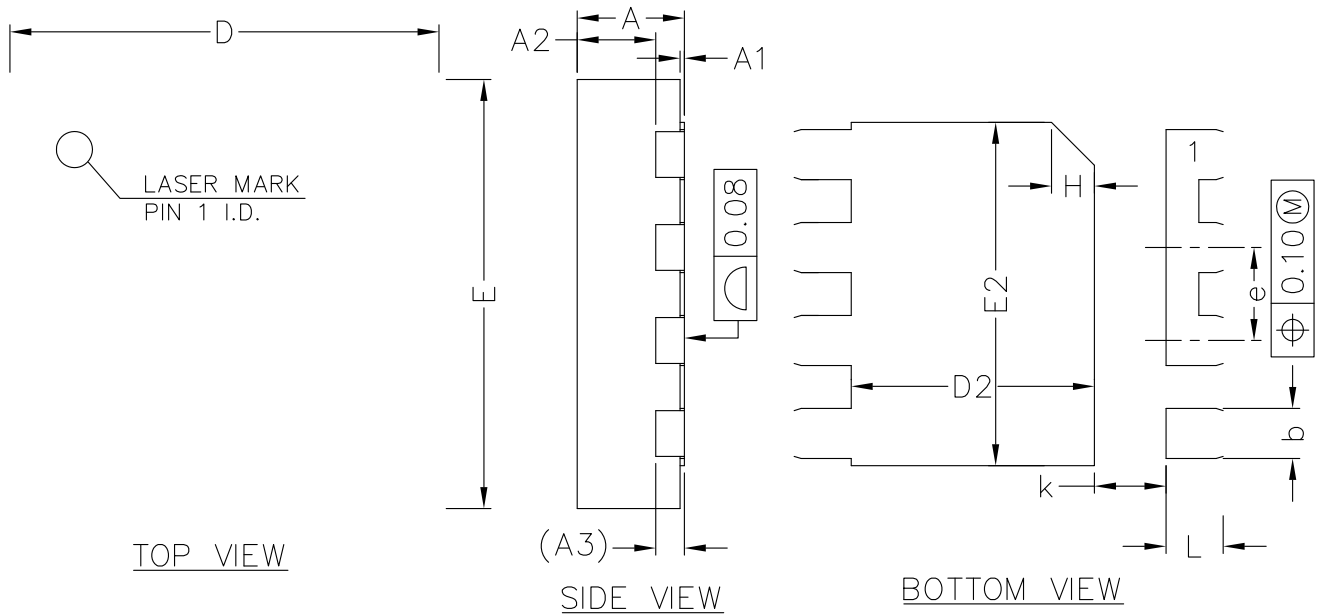
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A2	0.50	0.55	0.60
A3	0.20REF		
b	0.30	0.35	0.40
D	2.90	3.00	3.10
E	2.90	3.00	3.10
D2	1.60	1.70	1.80
E2	2.30	2.40	2.50
e	0.55	0.65	0.75
K	0.40	0.50	0.60
L	0.35	0.40	0.45

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